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(71) Applicant: CMC MATERIALS LLC [US/US]; 870 North Commons Drive, Aurora, Illinois 60504 (US).

(72) Inventors: LEE, Jaeseok; 870 North Commons Drive, Aurora, Illinois 60504 (US). TABERT, Jessica; 870 North Commons Drive, Aurora, Illinois 60504 (US). RAI, Satish;

870 North Commons Drive, Aurora, Illinois 60504 (US). KIM, Sangcheol; 870 North Commons Drive, Aurora, Illinois 60504 (US).

(74) Agent: OMHOLT, Thomas; CMC Materials LLC, 870 North Commons Drive, Aurora, Illinois 60504 (US).

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(54) Title: CHEMICAL MECHANICAL POLISHING PADS WITH A DISULFIDE BRIDGE

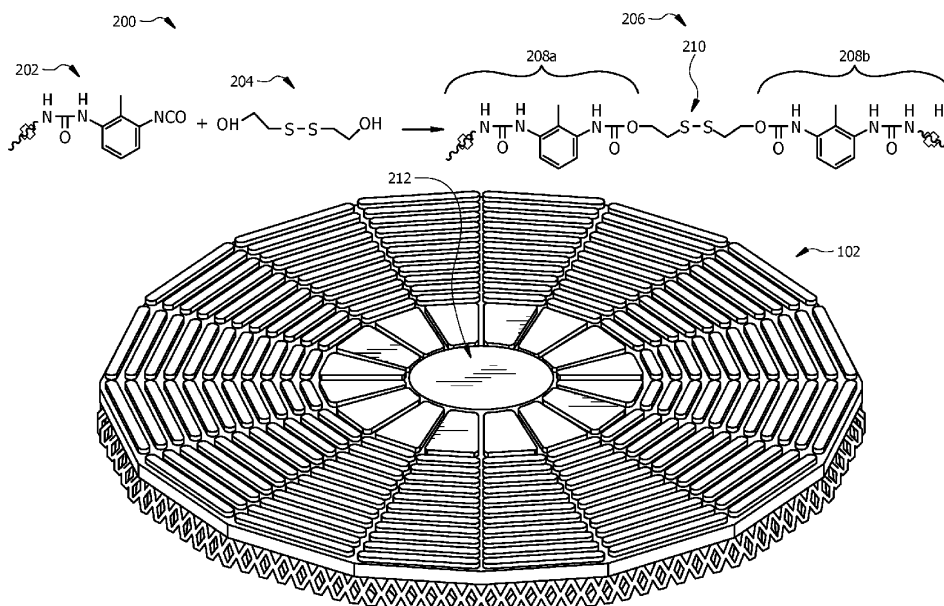


FIG. 2

(57) Abstract: A precursor for preparing a chemical mechanical polishing pad includes a prepolymer, a disulfide-containing component, and a curative. The chemical mechanical polishing pad prepared from the precursor includes a disulfide bridge in a polymer matrix. The disulfide bridge may include a disulfide bond capable of undergoing a chain exchange reaction at temperatures experienced during chemical mechanical polishing processes, resulting in rearrangement of nearby disulfide bonds during the chemical mechanical polishing processes rather than breakage of these bonds.

[Continued on next page]

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